

**Multistage MS Series Thermoelectric Cooler**

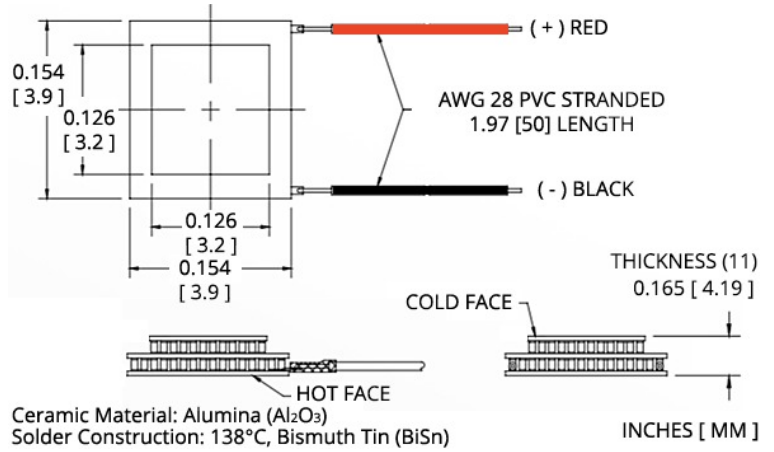
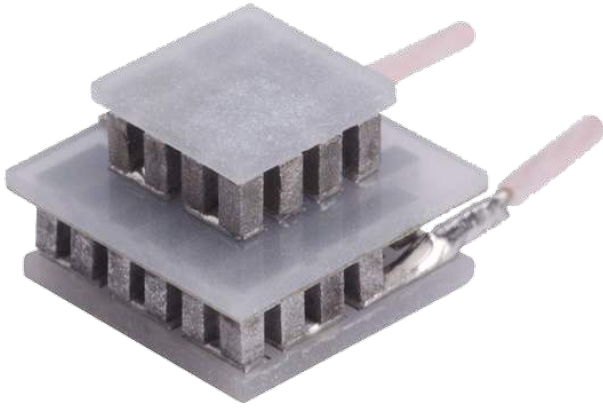
The MS2-010-06-06-11-11-11-W2 multistage thermoelectric cooler is able to reach colder temperatures than single stage thermoelectric coolers. It has a maximum  $Q_c$  of 0.3 Watts when  $\Delta T = 0$  and a maximum  $\Delta T$  of 94 °C at  $Q_c = 0$ .

**Features**

- High temperature differential
- Precise temperature control
- Reliable solid-state operation
- Environmentally-friendly
- DC operation
- RoHS-compliant

**Applications**

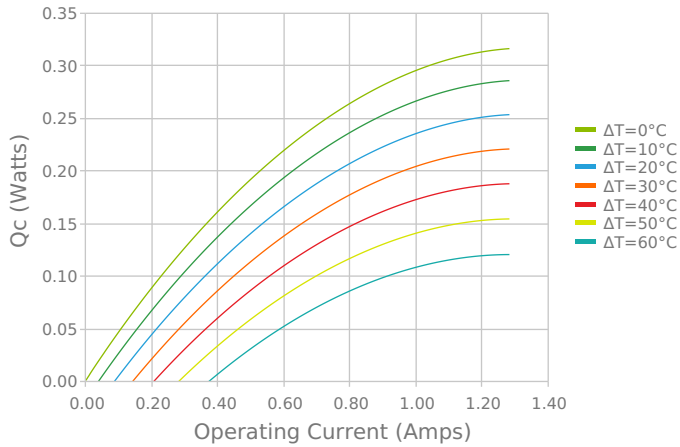
- Thermoelectric Cooling for CMOS Sensors
- Heads-Up Displays, Imaging Sensors



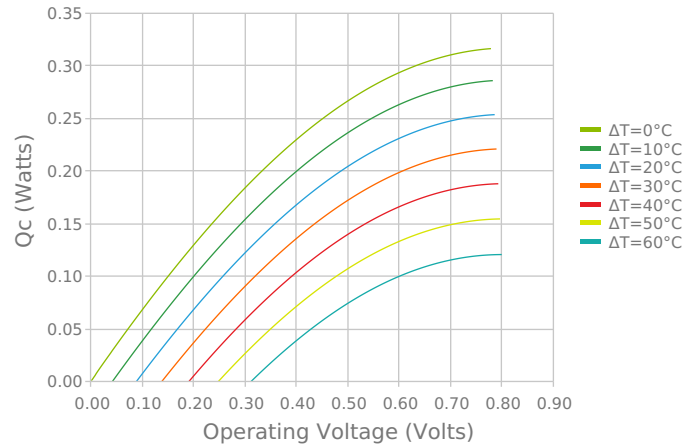
**ELECTRICAL AND THERMAL PERFORMANCE**

For maximum performance, be sure to orient the CONTROL side of the TEC against the application to be managed and the HEATSINK side against the heat sink or other heat rejection method. The CONTROL side is always opposite the side with lead attachments. Lead attachment is a passive heat loss and less impactful if located on the side that attaches to the heat exchanger.

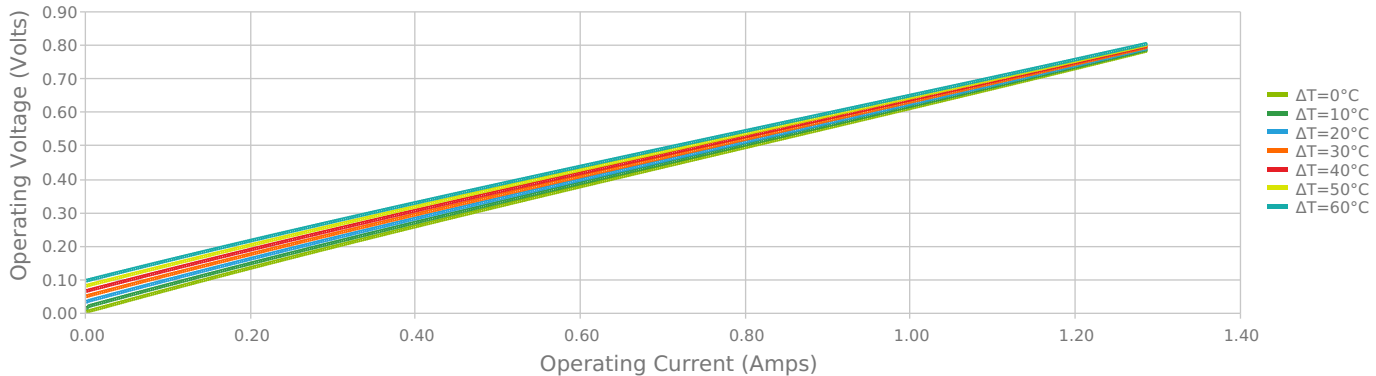
Heat Pumped at Cold Side  
 $T_{hot} = 27\text{ °C}$



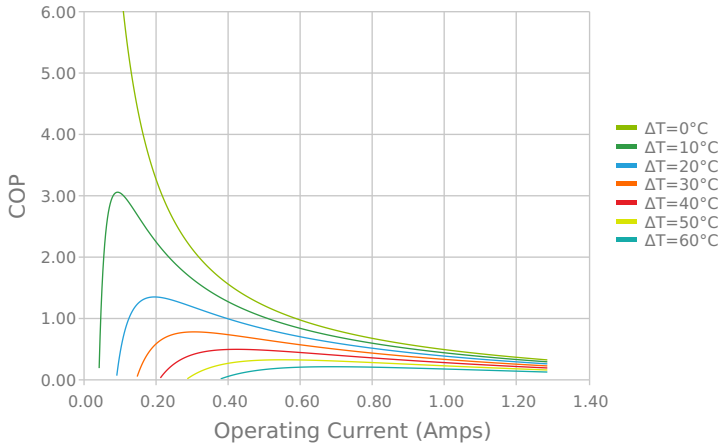
Heat Pumped at Cold Side  
 $T_{hot} = 27\text{ °C}$



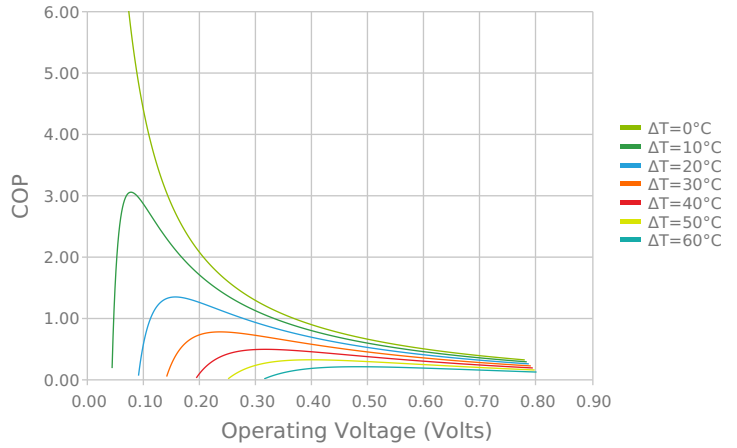
Current vs Voltage (I vs V)  
 $T_{hot} = 27\text{ °C}$



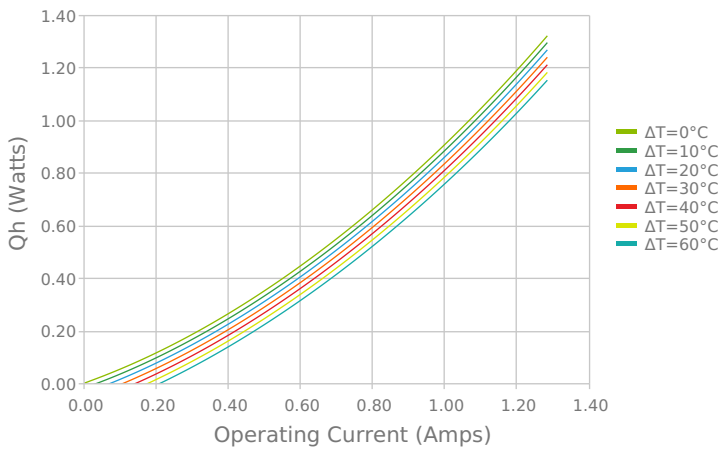
Coefficient of Performance (COP = Qc/Pin)  
Thot = 27 °C



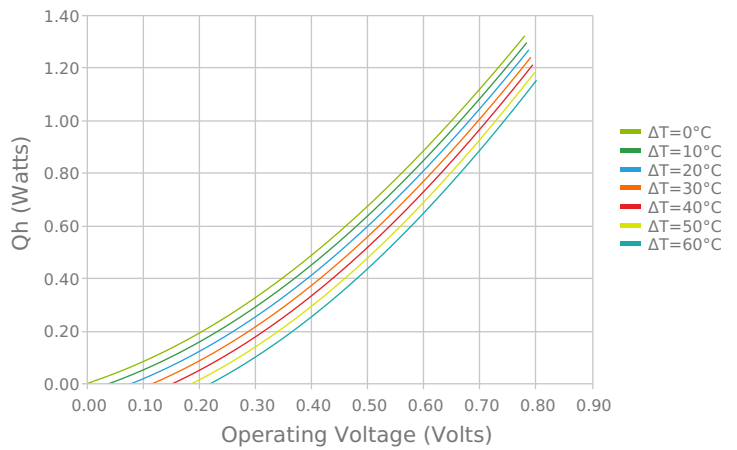
Coefficient of Performance (COP = Qc/Pin)  
Thot = 27 °C



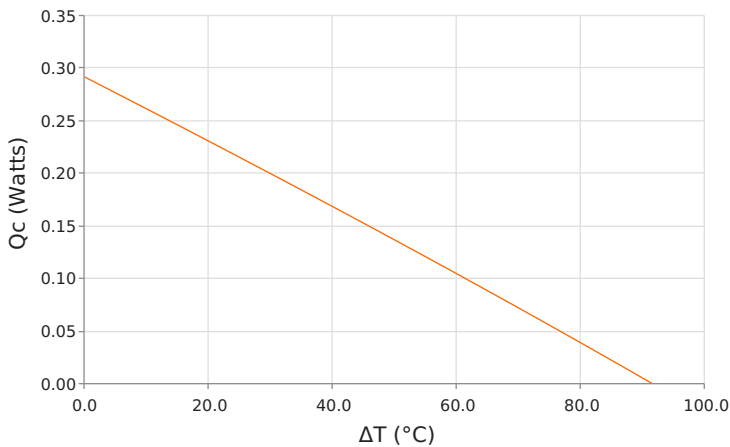
Total Heat Dissipated at Hot Side (Qh=Qc+Pin)  
Thot = 27 °C



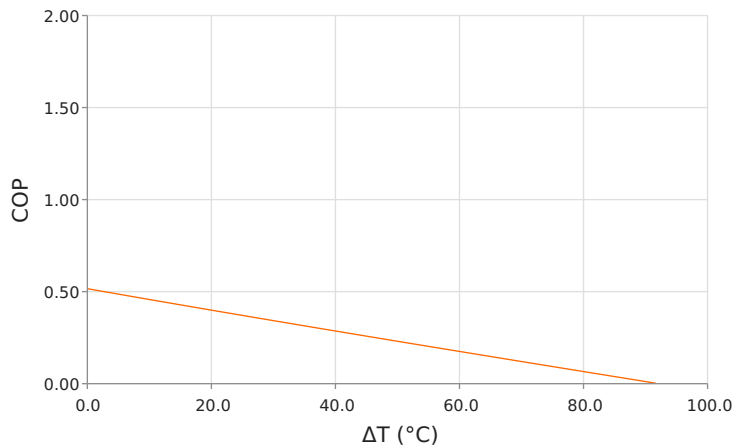
Total Heat Dissipated at Hot Side (Qh=Qc+Pin)  
Thot = 27 °C



Heat Pumped at Cold Side (Qc)  
Thot = 27 °C | Current = 1.0 Amps



Coefficient of Performance (COP = Qc/Pin)  
Thot = 27 °C | Current = 1.0 Amps



## SPECIFICATIONS\*

|   |                |
|---|----------------|
| <b>Hot Side Temperature</b>                               | <b>27.0 °C</b> |
| <b>Qcmax (<math>\Delta T = 0</math>)</b>                  | 0.3 Watts      |
| <b><math>\Delta T_{max}</math> (<math>Q_c = 0</math>)</b> | 94.0 °C        |
| <b>I<sub>max</sub> (I @ <math>\Delta T_{max}</math>)</b>  | 1.2 Amps       |
| <b>V<sub>max</sub> (V @ <math>\Delta T_{max}</math>)</b>  | 0.8 Volts      |
| <b>Module Resistance</b>                                  | 0.63 Ohms      |
| <b>Max Operating Temperature</b>                          | 80 °C          |
| <b>Weight</b>   | 1.0 gram(s)    |

\* Specifications reflect thermoelectric coefficients updated March 2020

## FINISHING OPTIONS

| Suffix | Thickness                            | Flatness / Parallelism                     | Hot Face | Cold Face | Lead Length        |
|--------|--------------------------------------|--|----------|-----------|--------------------|
| 11     | 4.200 ± 0.203 mm<br>0.165 ± 0.008 in | 0.025 mm / 0.203 mm<br>0.001 in / 0.008 in | Lapped   | Lapped    | 50.0 mm<br>1.97 in |

## SEALING OPTIONS

| Suffix | Sealant | Color | Temp Range | Description          |
|--------|---------|-------|------------|----------------------|
|        | None    |       |            | No sealing specified |

## NOTES

1. Max operating temperature: 80°C
2. Do not exceed I<sub>max</sub> or V<sub>max</sub> when operating module
3. Reference assembly guidelines for recommended installation
4. Solder tinning also available on metallized ceramics

Any information furnished by Laird and its agents, whether in specifications, data sheets, product catalogues or otherwise, is believed to be (but is not warranted as being) accurate and reliable, is provided for information only and does not form part of any contract with Laird. All specifications are subject to change without notice. Laird assumes no responsibility and disclaims all liability for losses or damages resulting from use of or reliance on this information. All Laird products are sold subject to the Laird Terms and Conditions of sale (including Laird's limited warranty) in effect from time to time, a copy of which will be furnished upon request.

© Copyright 2019-2022 Laird Thermal Systems, Inc. All rights reserved. Laird™, the Laird Ring Logo, and Laird Thermal Systems™ are trademarks or registered trademarks of Laird Limited or its subsidiaries.

Revision: 00 Date: 06-01-2022

Print Date: 06-13-2022